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TITLE: Adhesive-free adhesion between polymeric

surfaces using

free radical polymerisation proceeds to modify

the first

and the second substrates and contact them in

liquid

medium

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PATENT-ASSIGNEE: NAT SCI COUNCIL[NASCN]

PRIORITY-DATA: 1996TW-115919 (December 23, 1996)

PATENT-FAMILY:

PUB-NO PUB-DATE LANGUAGE

TW 314546 A September 1, 1997 ZH

JP 10182851 A July 7, 1998 JA

JP 3044206 B2 May 22, 2000 JA

APPLICATION-DATA:

PUB-NO APPL-DESCRIPTOR APPL-NO

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TW 314546A N/A 1996TW-115919

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INT-CL-CURRENT:

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ABSTRACTED-PUB-NO: TW 314546 A

BASIC-ABSTRACT:

A manufacturing method for adhesion between polymeric substrate

includes the

following steps: (a) Firstly functional monomer with free radical polymerization proceeds surface graft polymerization to modify the surface of

first polymeric substrates. (b) Secondly functional monomer with free radical

polymerization proceeds surface graft polymerization to modify the surface of

second polymeric substrates. (c) The surface of firstly and secondly modified

polymeric substrates contacts each other under liquid medium. (d) Keep contact

for some time until liquid medium to be dry.

TITLE-TERMS: ADHESIVE FREE POLYMERISE SURFACE RADICAL PROCEED MODIFIED FIRST

SECOND SUBSTRATE CONTACT LIQUID MEDIUM

DERWENT-CLASS: A35

CPI-CODES: A10-C03A; A11-B09D; A11-C01D; A12-S06C1;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1]

018; P0000; L9999 L2802; H0088 H0011; L9999 L2573 L2506; Polymer Index [1.2]

018; ND07; N9999 N5721\*R; N9999 N7192 N7023; Q9999 Q7818\*R; K9574

K9483; K9687 K9676; K9676\*R; K9712 K9676;
Polymer Index [1.3]
 018; C999 C088\*R C000; C999 C271;

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